

New Software Version 1.13

For mModule iDOC

Product Update, October 2006

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Description

- A new software version 1.13 has been released for mModule™ iDOC. This version replaces the current software version 1.12 in all mModule iDOC configurations and capacities. The new software version offers support for the SLC NAND flash components that are manufactured using the 60 nm process, commonly available in today's market.
- A new capacity has been released – 2048MB.
- Table 1 shows updated CHS parameters for the following capacities: 1024MB, 1536MB & 2048MB. CHS parameters to lower capacities remain the same.

Table 1: Updated CHS parameters

iDiskOnChip Capacity	CHS Parameters					
	Cylinder		Head		Sector	
	V1.12	V1.13	V1.12	V1.13	V1.12	V1.13
1024MB	2044	2026	16	16	63	63
1536MB	3067	3052	16	16	63	63
2048MB	-	4066	-	16	-	63

- Table 2 shows the specification of the updated versions according to capacities and configurations:

Table 2: Updated Versions according to Capacities and Configurations

Capacity [MB]	Vertical 40	Vertical 44	Horizontal 40	Horizontal 44
32 PB Free	A 1.12	A 1.12	A 1.12	A 1.12
64 PB Free	A 1.12	A 1.12	A 1.12	A 1.12
128 PB Free	A 1.12	A 1.12	A 1.12	A 1.12
256 PB Free	E 1.13	C 1.13	C 1.13	C 1.13
512 PB Free	E 1.13	C 1.13	C 1.13	C 1.13
768 PB Free	E 1.13	C 1.13	C 1.13	C 1.13
1024 PB Free	E 1.13	C 1.13	C 1.13	C 1.13
1536 PB Free	E 1.13	C 1.13	C 1.13	C 1.13
2048 PB Free	E 1.13	C 1.13	C 1.13	C 1.13

Reason for Change

The new software version 1.13 supports the new 60nm flash process, which offers better cost structure to mModule iDOC customers, as well as improved flash availability.

Availability

November, 2006

How to Contact Us

Please contact your msystems representative or visit the mModule web page on the msystems website (www.m-systems.com) for any further information or assistance.

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